





PCT

INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY (Chapter II of the Patent Cooperation Treaty)

(PCT Article 36 and Rule 70)

(FC) Attack 30 and Rule 70)						
Applicant's or agent's file reference NTK03-1574WO	FOR FURTHER AC	TION	See Form PCT/IPEA/416			
International application No. PCT/JP2003/014989	International filing date 25 November 200		Priority date (day/month/year) 26 November 2002 (26.11.2002)			
International Patent Classification (IPC) or n G11B 21/21, 5/60, H05K 1/02		<u> </u>	20 November 2002 (20.11.2002)			
Applicant N	IPPON STEEL CHI	EMICAL CO., LT	TD.			
Authority under Article 35 and trans 2. This REPORT consists of a total of 3. This report is also accompanied by a. (sent to the applicant and sheets of the descand/or sheets con Administrative Ir	4 sheets, ANNEXES, comprising: I to the International Bureription, claims and/or distaining rectifications audistructions).	including this cover areau) a total of	sheet.			
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Box No. IV Lack of unity Box No. V Reasoned star citations and Box No. VI Certain documents of the company of	eport ment of opinion with restriction terment under Article 35(explanations supporting	gard to novelty, inver 2) with regard to nov such statement	ntive step and industrial applicability relty, inventive step or industrial applicability;			
Date of submission of the demand		Date of completion	of this report			
01 June 2004 (01.06.	2004)		February 2005 (02.02.2005)			
Name and mailing address of the IPEA/JP		Authorized officer	· · · · · · · · · · · · · · · · · · ·			
Facsimile No.		Telephone No.				



INTERNATIONAL PRELIMINARY REPORT ON PATENTABILITY

Internation No.

PCT/JP2003/014989

Box No.	I Basis of the report
	regard to the language, this report is based on the international application in the language in which it was filed, unless wise indicated under this item.
	This report is based on translations from the original language into the following language, which is language of a translation furnished for the purpose of:
	international search (under Rules 12.3 and 23.1(b))
	publication of the international application (under Rule 12.4)
	international preliminary examination (under Rules 55.2 and/or 55.3)
furnis	regard to the elements of the international application, this report is based on (replacement sheets which have been shed to the receiving Office in response to an invitation under Article 14 are referred to in this report as "originally filed" tre not annexed to this report):
	The international application as originally filed/furnished
	the description: pages , as originally filed/furnished
	pages, as originally filed/turnished pages* received by this Authority on
	pages* received by this Authority on
	the claims:
l	pages , as originally filed/furnished
	pages*, as amended (together with any statement) under Article 19
	pages* received by this Authority on
	pages* received by this Authority on
	the drawings:
_	pages, as originally filed/furnished
	pages* received by this Authority on
	pages* received by this Authority on
	a sequence listing and/or any related table(s) - see Supplemental Box Relating to Sequence Listing.
3. 🔲	The amendments have resulted in the cancellation of:
_	the description, pages
	the claims, Nos.
	the drawings, sheets/figs
	the sequence listing (specify):
	any table(s) related to sequence listing (specify):
	any and to so the source instants (upocogy).
4.	This report has been established as if (some of) the amendments annexed to this report and listed below had not been made, since they have been considered to go beyond the disclosure as filed, as indicated in the Supplemental Box (Rule 70.2(c)).
	the claims, Nos the drawings, sheets/figs
	the sequence listing (specify):
	any table(s) related to sequence listing (specify):
* If ite	m 4 applies, some or all of those sheets may be marked "superseded."

V.	Reasoned statement under Article 35(2) with regard to novelty, inventive step or industrial applicability
• •	citations and explanations supporting such statement

Statement			
Novelty (N)	Claims	1-6	YES
	Claims		NO
Inventive step (IS)	Claims		YES
	Claims	1-6	NO NO
Industrial applicability (IA)	Claims	1-6	YES
	Claims		NO

Citations and explanations

Document 1: JP 11-154314 A (Ube Industries, Ltd.), 8

June 1999, claim 6, paragraph [0006],

paragraphs [0012]-[0014], paragraph [0026],

fig. 1

Document 2: JP 2002-317231 A (Nippon Mining & Metals Co., Ltd.), 31 October 2002, entire text

Document 3: JP 11-264040 A (Nippon Mining & Metals Co., Ltd.), 28 September 1999, entire text

The inventions described in claims 1 to 6 do not involve an inventive step in the light of documents 1 to 3 cited in the international search report.

Document 1 (paragraphs [0012] to [0014]) discloses a method for manufacturing a magnetic head suspension device wherein copper foil, a polyimide resin, and a stainless steel substrate are strongly bonded together using a hot press or thermal pressure bonding at 280° or greater. Further, in paragraph [0014], document 1 also indicates that standard copper foil such as rolled copper foil can be used as the copper foil for circuitry. In paragraphs [0006] and [0008], document 1 also indicates that the thickness of the copper foil can be 5 to 35 μm , and the

thickness of the polyimide resin layer can be 0.5 to 20 $\mu m_{\rm }$ preferably 1 to 10 $\mu m_{\rm }$

Document 2 (paragraph [0003]) discloses the use of a copper alloy foil approximately 18 μm thick in a hard disk drive suspension. In paragraph [0004], document 2 also indicates that the thickness of a stainless steel substrate should be approximately 20 μm . Further, line 12 of table 2 on page 6 indicates a tensile strength of 803 N/mm² and a conductivity of 57% IACS.

Document 3 (paragraph [0005]) discloses the use of a printed circuit board as a drive circuit substrate inside a hard disk. In paragraph [0006], document 3 also indicates that a material with sufficient strength and electric conductivity is required. Further, comparison alloy 2 in table 1 on page 5 is shown as having a tensile strength of 461 N/mm² and a conductivity of 65% IACS.